



Confirmation No.: 7484

Examiner: M. Wilczewski

Art Unit: 2822

Docket No.: H010011

METAL BUMP WITH AN INSULATING SIDEWALL AND METHOD OF

**FABRICATING THEREOF** 

09/764,207

January 19, 2001

## **RESPONSE TO THE RESTRICTION REQUIREMENT**

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Ming-Yi LAY, et al.

Serial No.:

Filed:

For:

August 29, 2003

Sir:

In response to the Restriction Requirement dated June 6, 2003, with the period for response being due on September 6, 2003, Applicants hereby elect to prosecute Group I Claims 1-10 (drawn to a structure comprising a plurality of metal bumps for connecting a non-conducting substrate and a chip, classified in class 257, subclass 678+) without traverse. Applicants reserve the right to file a divisional application directed to non-elected claims.

If any additional fees are due with regard to this paper, please charge counsel's Deposit Account No. 50-2394.

Respectfully submitted,

IPS, Inc.

Robert J. Forsell, Ji

Reg. No. 51,693

5 **250**0000001 502394

09764207

Customer No. 34003 5717 Colfax Avenue Alexandria, VA 22311 Tel: (703) 379-9625

Fax: (703) 379-9628

RJF/km